

D1FS6A

Schottky Barrier Diodes
60V, 2.5A

Feature

- Small SMD
- High Recovery Speed
- Low V_F
- Based on AEC-Q101
- Pb free terminal
- RoHS:Yes

OUTLINE

Package (House Name): 1F
Package (JEDEC Code): DO-214AC



Equivalent circuit



Absolute Maximum Ratings (unless otherwise specified : $T_I=25^\circ\text{C}$)

Item	Symbol	Conditions	Ratings	Unit
Storage temperature	T_{STG}		-55 to 150	°C
Junction temperature	T_J		-55 to 150	°C
Repetitive peak reverse voltage	V_{RRM}		60	V
Average forward current	$I_F(AV)$	50Hz sine wave, Resistance load, $T_I=103^\circ\text{C}$	2.5	A
Average forward current	$I_F(AV)$	50Hz sine wave, Resistance load, On alumina substrate, $T_a=25^\circ\text{C}$ ※	1.5	A
Average forward current	$I_F(AV)$	50Hz sine wave, Resistance load, On glass-epoxy substrate, $T_a=25^\circ\text{C}$ ※	1	A
Surge forward current	I_{FSM}	50Hz sine wave, Non-repetitive, 1cycle, Peak value, $T_J=25^\circ\text{C}$	60	A

※ : See the original Specifications

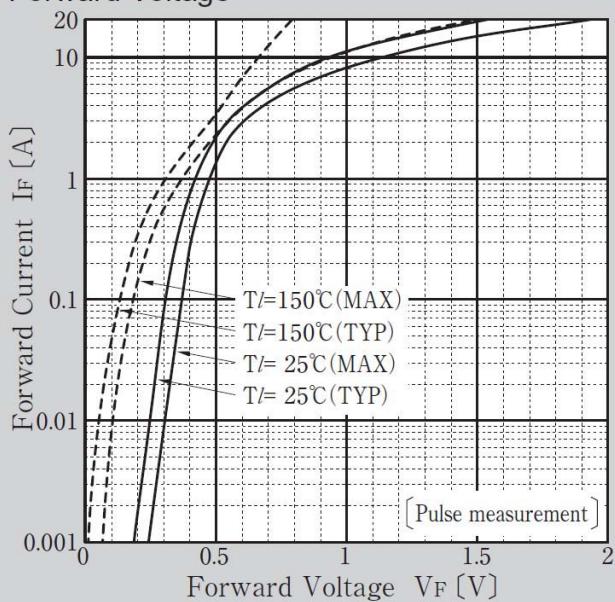
Electrical Characteristics (unless otherwise specified : Tl=25°C)

Item	Symbol	Conditions	Ratings			Unit
			MIN	TYP	MAX	
Forward voltage	V_F	IF=2.5A, Pulse measurement			0.57	V
Forward voltage	V_F	IF=1A, Pulse measurement			0.47	V
Reverse current	I_R	VR=60V, Pulse measurement			0.2	mA
Total capacitance	C_t	f=1MHz, VR=10V		80		pF
Thermal resistance	$R_{th(j-l)}$	Junction to lead			23	°C/W
Thermal resistance	$R_{th(j-a)}$	Junction to ambient, On alumina substrate	※		108	°C/W
Thermal resistance	$R_{th(j-a)}$	Junction to ambient, On glass-epoxy substrate	※		157	°C/W

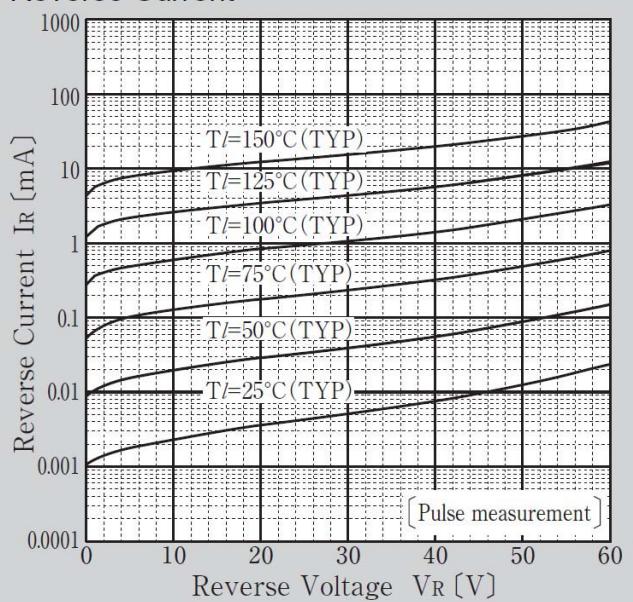
※ :See the original Specifications

CHARACTERISTIC DIAGRAMS

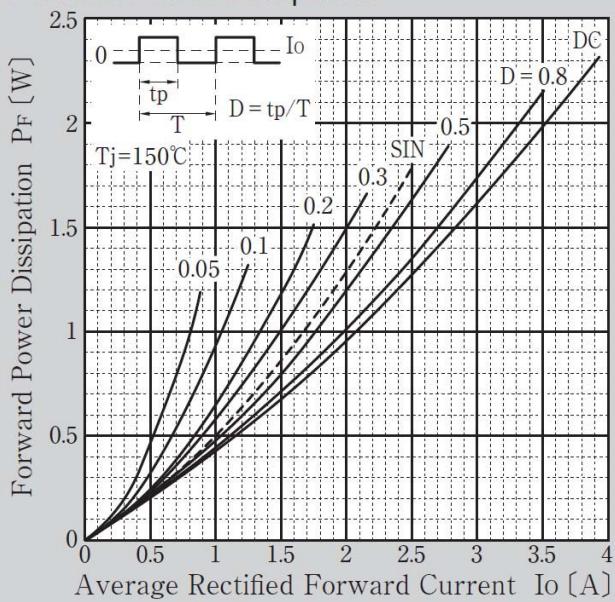
Forward Voltage



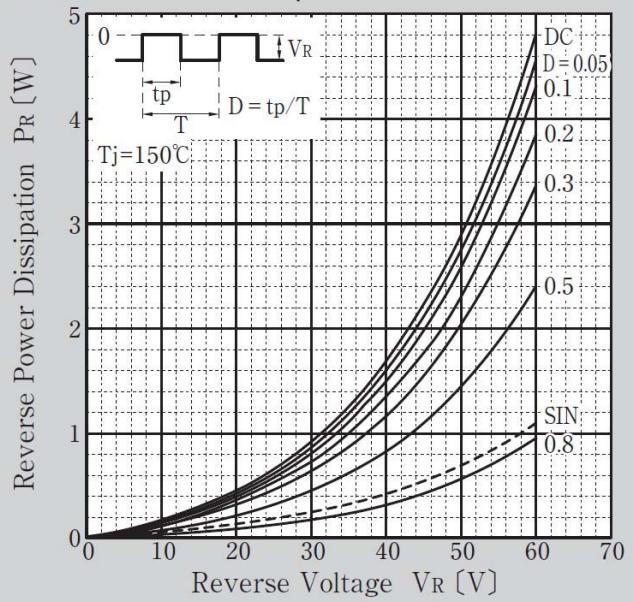
Reverse Current

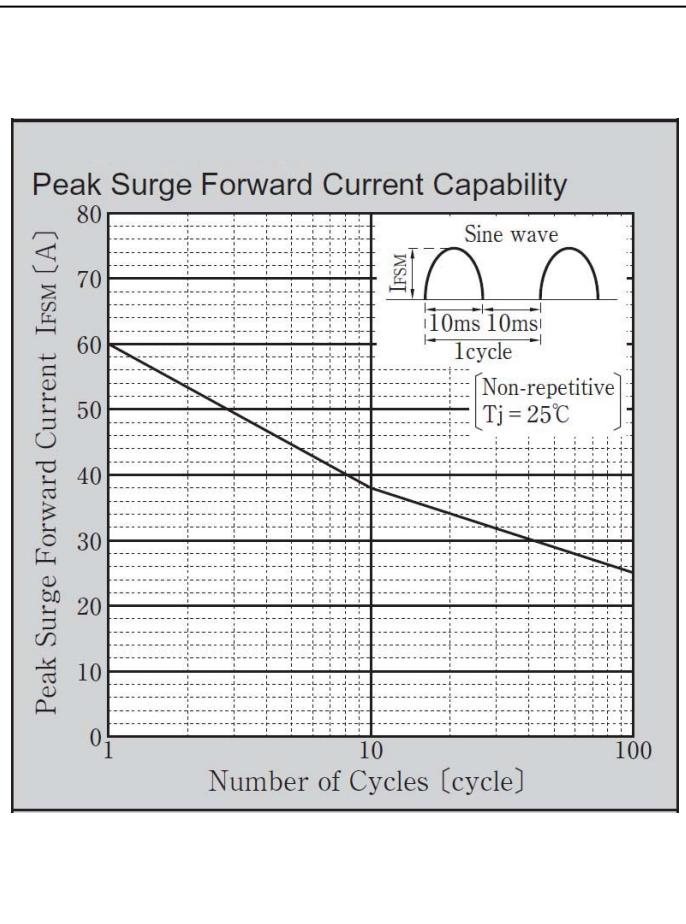
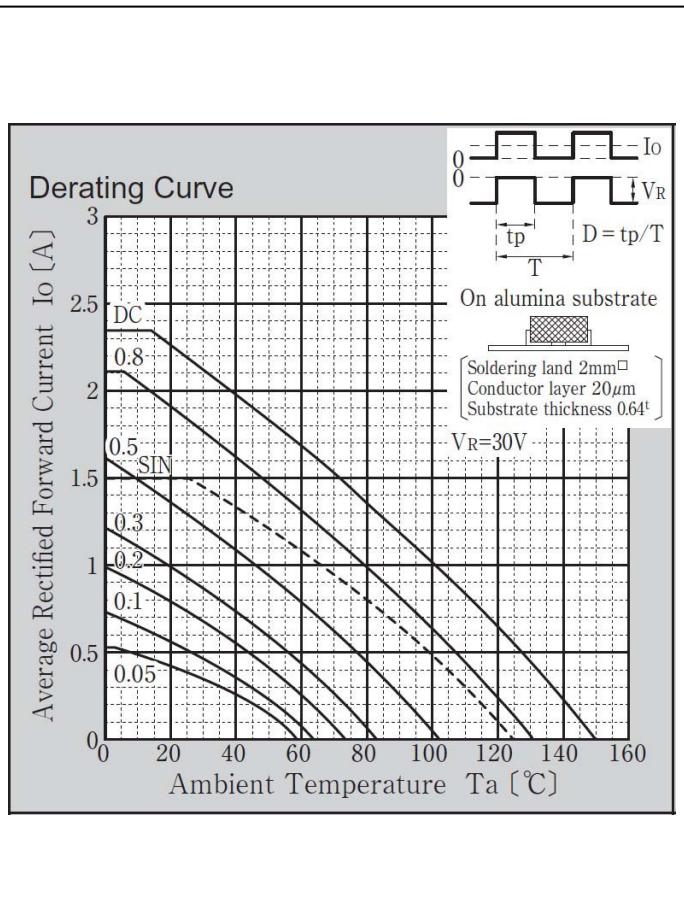
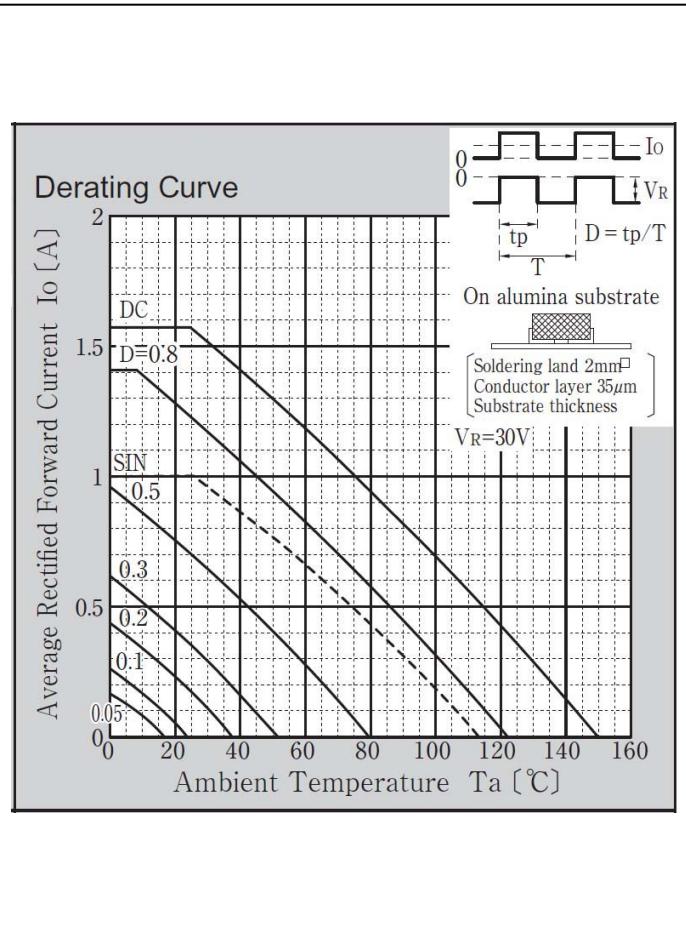
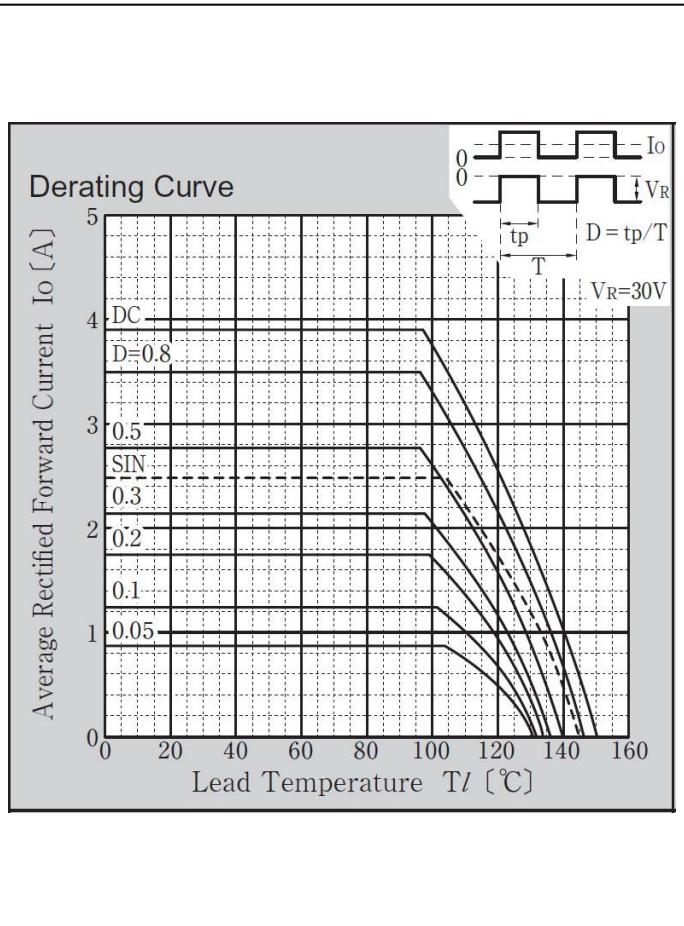


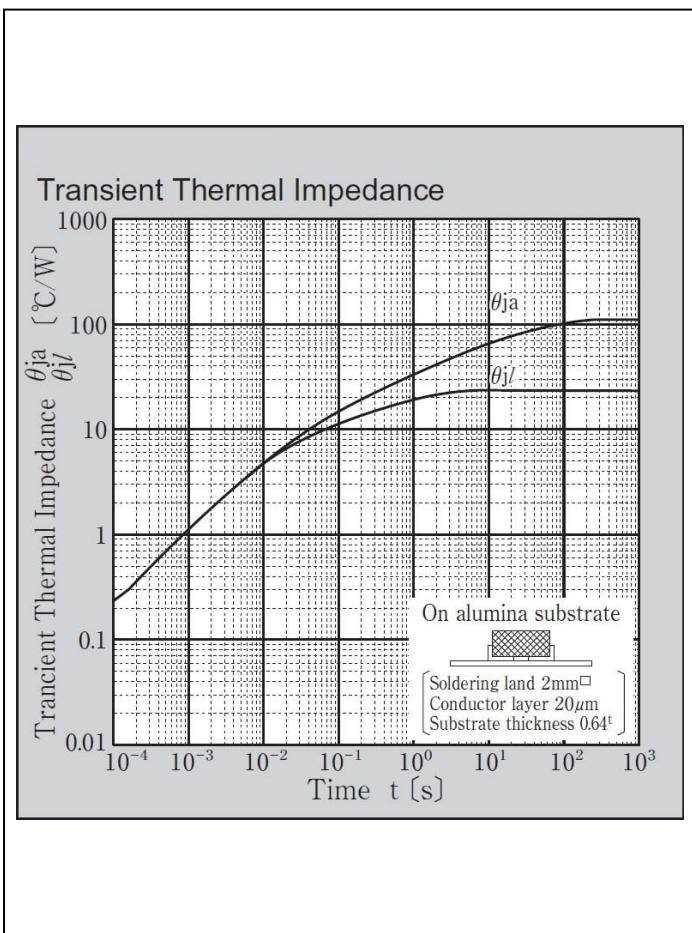
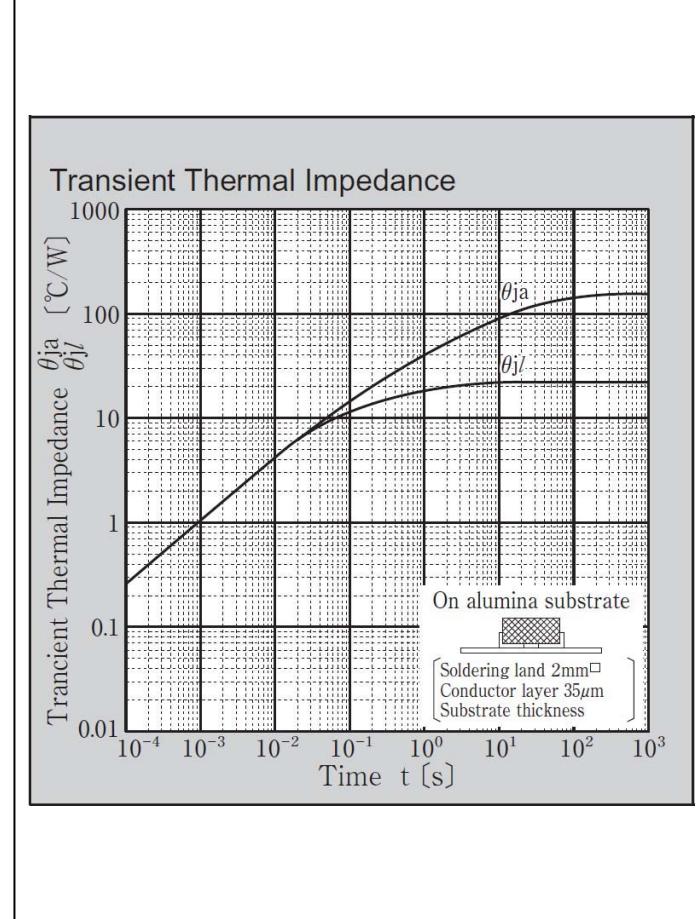
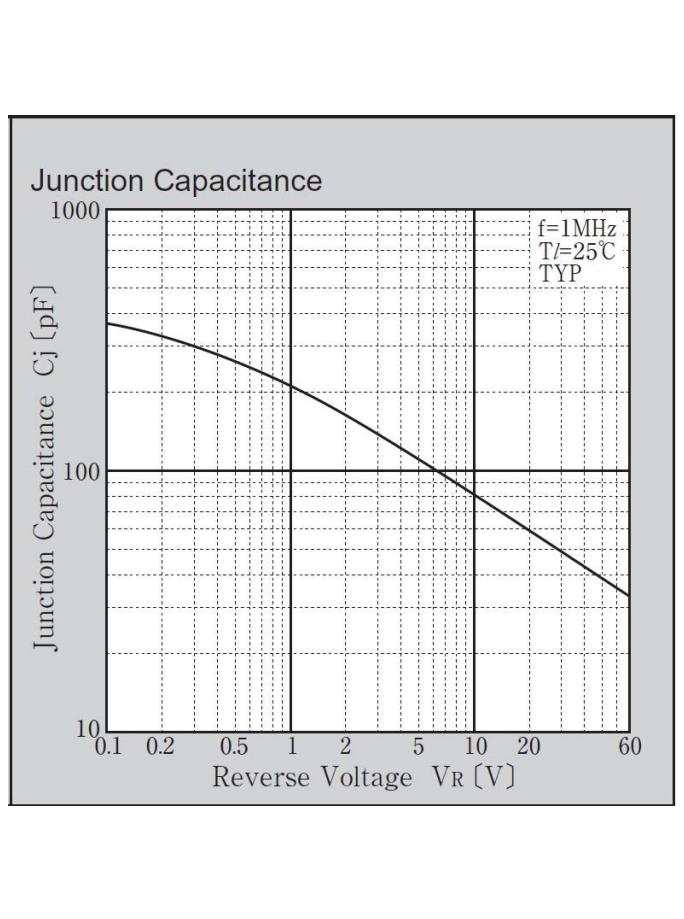
Forward Power Dissipation



Reverse Power Dissipation







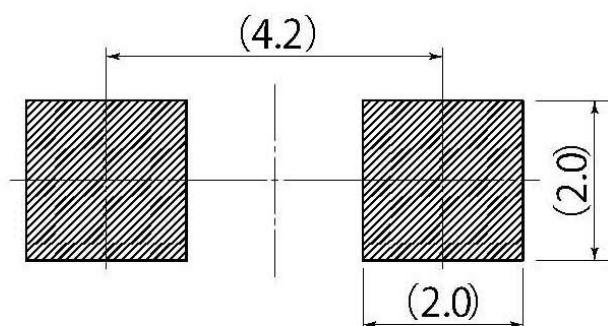
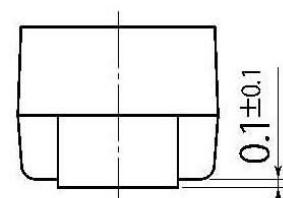
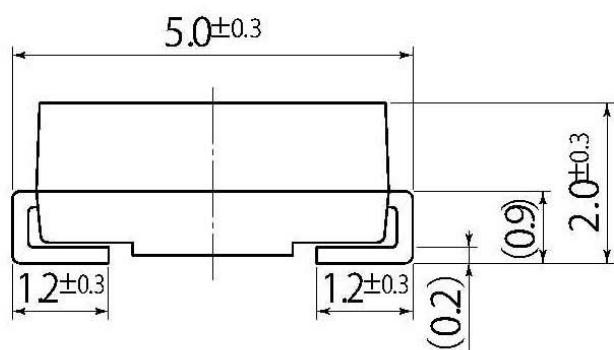
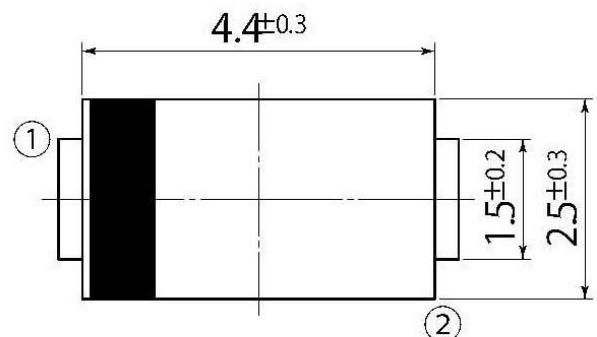
Outline Dimensions

unit:mm

scale: 10/1

B3

JEDEC Code	DO-214AC
JEITA Code	—
House Name	1F, CF



Referential Soldering Pad

- Optimize soldering pad to the board design and soldering condition.

Notes

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